



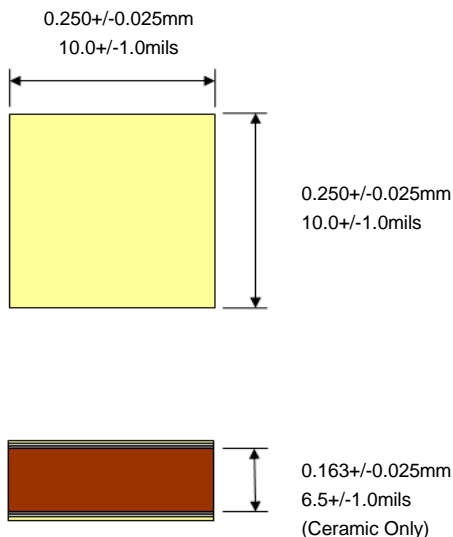
TECDIA CO., LTD.

2F Tamachi Kiyota Bldg.

4-3-4 Shibaura Minato-ku, Tokyo 108-0023 Japan

TEL: 81-3-5765-5400 FAX: 81-3-5765-5404

## SPECIFICATION SHEET



Manufactured to metric dimensions. Imperial units are for reference only.

Part Number:	CMS1R0K1BC
Dielectric Constant(K):	280
Capacitance Value:	1[pF] @ 1MHz, 1 Vrms, 25°C, No DC Bias
Capacitance tolerance:	K (tolerance: $\pm 10\%$ )
Dissipation Factor (DF):	0.25% Max @ 1MHz, 1 Vrms, 25°C, No DC Bias
Rated working voltage (RWV):	50 V
Insulation Resistance (IR):	100,000M $\Omega$ Min @ 50Vdc, 25°C
Dielectric Withstanding Voltage (DWV):	No breakdown @ 125Vdc x 2sec, 25°C
Temperature Characteristic of Capacitance:	-1000 $\pm$ 250 ppm/°C (M3K @ -55°C to +125°C) @ No DC Bias
Metallization:	
Top:	TiW-Pt - Au 2.5 $\mu$ m Min
Bottom:	TiW-Pt - Au 2.5 $\mu$ m Min

### NOTES:

- Other specifications not listed are available at [www.tecdia.com](http://www.tecdia.com).
  - Specifications may be subject to change without prior notice.
  - RoHS compliant.
  - Wire bonding location should be 25 $\mu$ m or further from edges of the electrode to avoid electrode peeling.
  - Capacitance, Temperature Coefficient and Dissipation Factor are measured before any AC or DC bias has been applied.
  - Recommended Storage Conditions (Waffle Packaging): 23  $\pm$  10°C @ 60% RH Max
  - Guaranteed Shelf Life: 1 year after delivery under recommended storage conditions.
  - Successful wire bonding and die attachment are dependent on the types of bonding tools and conditions used. Please check the wire bonding and die attach conditions of your site to prevent the wire/electrode from peeling or detaching.
- Tecdia is not responsible for mechanical issues such as cracking or detaching that can occur when solder die mounting.

PREPARED BY:

M. Simpson

2020/1/14

DESCRIPTION:

CHIP CAPACITOR

Scale: Not to Scale

APPROVED BY:

T. Yoshikawa

2020/1/14

TECDIA PART NUMBER:

CMS1R0K1BC

SHEET:

1 of 1